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IN : OKADA YUKO  
 PA : SOKEN KAGAKU KK  
 TI : COVERING PARTICLE AND ANISOTROPICALLY CONDUCTIVE ADHESIVE  
 AB : PURPOSE: To realize excellent initial conductivity by heating and press-fitting, and hold the excellent initial conductivity even when bonded substrates are used under severe conditions.

CONSTITUTION: In an anisotropically conductive adhesive, two substrates 18a, 18b each having an electrically connected portion on the observe thereof are thermally press-fitted to each other in such a manner that the electrically connected portions face to each other via an adhesive 21 where conductive particles 15 are dispersed in an insulative adhesive component, so that the electrically connected portions of the substrates 18a, 18b are electrically conducted in the pressurizing direction. The conductive particle 15 comprises an insulative core material 1, a conductive layer 2 formed on the core material 1, and an insulative layer 3 for covering 0.1-99.9% of the area of the conductive layer 2, where a covering particle for discontinuously covering the conductive layer 2 is used.

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